

TC74AC174P, TC74AC174F, TC74AC174FN, TC74AC174FT

HEX D-TYPE FLIP FLOP WITH CLEAR

The TC74AC174 is an advanced high speed CMOS HEX D-TYPE FLIP FLOP fabricated with silicon gate and double-layer metal wiring C²MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

Information signals applied to D inputs are transferred to the Q output on the positive going edge of the clock pulse.

When the $\overline{\text{CLR}}$ input is held low, the Q output are in the low logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

FEATURES :

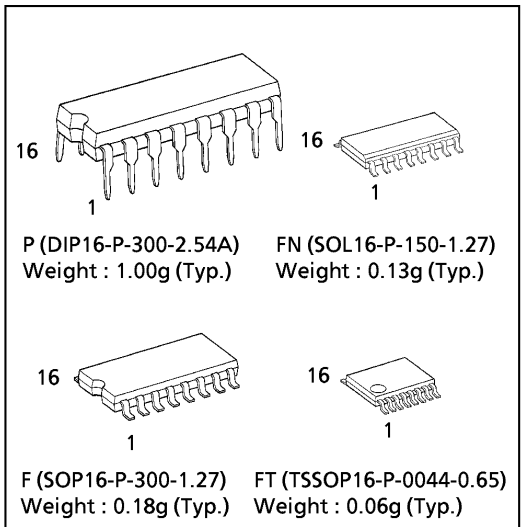
- High Speed..... $f_{\text{MAX}} = 180\text{MHz}(\text{typ.})$
at $V_{\text{CC}} = 5\text{V}$
- Low Power Dissipation..... $I_{\text{CC}} = 8\mu\text{A}(\text{Max.})$ at $T_a = 25^\circ\text{C}$
- High Noise Immunity..... $V_{\text{NIH}} = V_{\text{NIL}} = 28\% V_{\text{CC}} (\text{Min.})$
- Symmetrical Output Impedance... $|I_{\text{OH}}| = I_{\text{OL}} = 24\text{mA}(\text{Min.})$
Capability of driving 50Ω transmission lines.
- Balanced Propagation Delays..... $t_{\text{pLH}} \approx t_{\text{pHL}}$
- Wide Operating Voltage Range... $V_{\text{CC}} (\text{opr}) = 2\text{V} \sim 5.5\text{V}$
- Pin and Function Compatible with 74F174

TRUTH TABLE

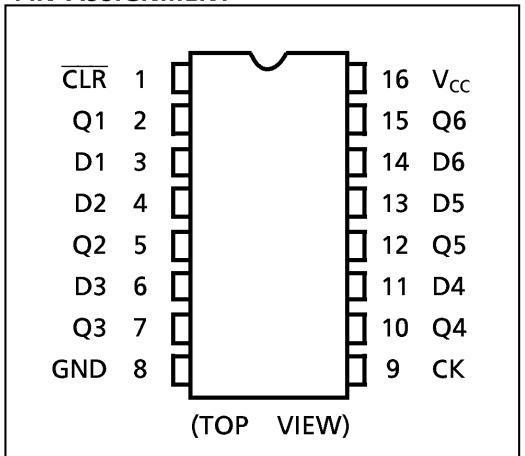
INPUTS			OUTPUTS	FUNCTION
$\overline{\text{CLR}}$	D	CK	Q	
L	X	X	L	CLEAR
H	L		L	—
H	H		H	—
H	X		Q _n	NO CHANGE

X : Don't Care

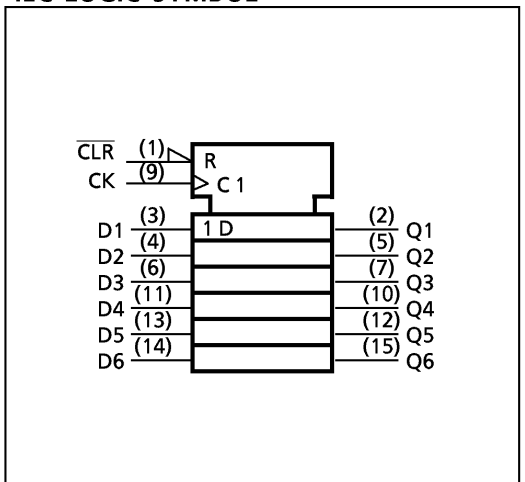
(Note) The JEDEC SOP (FN) is not available in Japan.



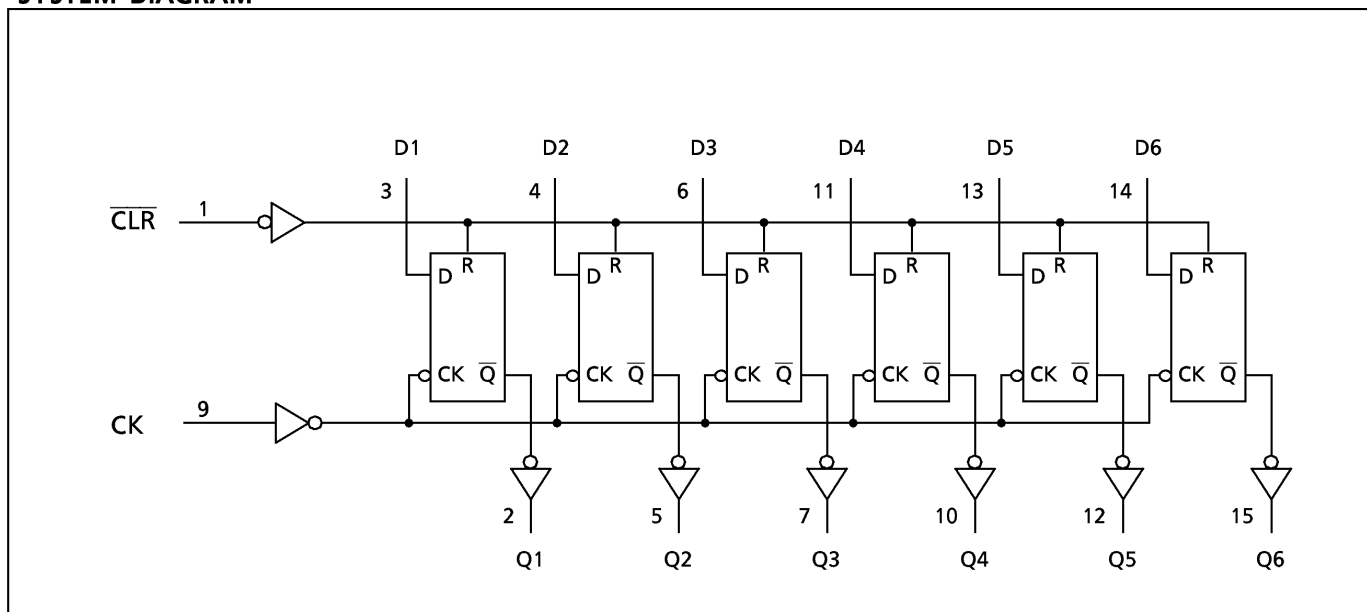
PIN ASSIGNMENT



IEC LOGIC SYMBOL



SYSTEM DIAGRAM



ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage Range	V_{CC}	-0.5~7.0	V
DC Input Voltage	V_{IN}	-0.5~ $V_{CC} + 0.5$	V
DC Output Voltage	V_{OUT}	-0.5~ $V_{CC} + 0.5$	V
Input Diode Current	I_{IK}	± 20	mA
Output Diode Current	I_{OK}	± 50	mA
DC Output Current	I_{OUT}	± 50	mA
DC V_{CC} /Ground Current	I_{CC}	± 150	mA
Power Dissipation	P_D	500 (DIP)* / 180 (SOP/TSSOP)	mW
Storage Temperature	T_{stg}	-65~150	°C

*500mW in the range of $T_a = -40^{\circ}C \sim 65^{\circ}C$. From $T_a = 65^{\circ}C$ to $85^{\circ}C$ a derating factor of $-10mW/^{\circ}C$ should be applied up to 300mW.

RECOMMENDED OPERATING CONDITIONS

PARAMETER	SYMBOL	VALUE	UNIT
Supply Voltage	V_{CC}	2.0~5.5	V
Input Voltage	V_{IN}	0~ V_{CC}	V
Output Voltage	V_{OUT}	0~ V_{CC}	V
Operating Temperature	T_{opr}	-40~85	°C
Input Rise and Fall Time	dt/dV	0~ 100 ($V_{CC} = 3.3 \pm 0.3V$) 0~ 20 ($V_{CC} = 5 \pm 0.5V$)	ns/V

DC ELECTRICAL CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C			Ta = -40~85°C		UNIT	
				MIN.	TYP.	MAX.	MIN.	MAX.		
High - Level Input Voltage	V _{IH}		2.0	1.50	—	—	1.50	—	V	
			3.0	2.10	—	—	2.10	—		
			5.5	3.85	—	—	3.85	—		
Low - Level Input Voltage	V _{IL}		2.0	—	—	0.50	—	0.50	V	
			3.0	—	—	0.90	—	0.90		
			5.5	—	—	1.65	—	1.65		
High - Level Output Voltage	V _{OH}	V _{IN} = V _{IH} or V _{IL}	I _{OH} = -50μA	2.0	1.9	2.0	—	1.9	—	V
				3.0	2.9	3.0	—	2.9	—	
			I _{OH} = -4mA I _{OH} = -24mA I _{OH} = -75mA*	3.0	2.58	—	—	2.48	—	
				4.5	3.94	—	—	3.80	—	
Low - Level Output Voltage	V _{OL}	V _{IN} = V _{IH} or V _{IL}	I _{OL} = 50μA	2.0	—	0.0	0.1	—	0.1	V
				3.0	—	0.0	0.1	—	0.1	
			I _{OL} = 12mA I _{OL} = 24mA I _{OL} = 75mA*	3.0	—	—	0.36	—	0.44	
				4.5	—	—	0.36	—	0.44	
5.5	—	—	—	—	1.65	—				
Input Leakage Current	I _{IN}	V _{IN} = V _{CC} or GND	5.5	—	—	±0.1	—	±1.0	μA	
Quiescent Supply Current	I _{CC}	V _{IN} = V _{CC} or GND	5.5	—	—	8.0	—	80.0		

* : This spec indicates the capability of driving 50Ω transmission lines.

One output should be tested at a time for a 10ms maximum duration.

TIMING REQUIREMENTS (Input t_r = t_f = 3ns)

PARAMETER	SYMBOL	TEST CONDITION	V _{CC} (V)	Ta = 25°C	Ta = -40~85°C	UNIT
				LIMIT	LIMIT	
Minimum Pulse Width (CK)	t _W (L) t _W (H)		3.3 ± 0.3	7.0	7.0	ns
			5.0 ± 0.5	5.0	5.0	
Minimum Pulse Width (CLR)	t _W (L)		3.3 ± 0.3	7.0	7.0	
			5.0 ± 0.5	5.0	5.0	
Minimum Set - up Time	t _s		3.3 ± 0.3	7.0	7.0	
			5.0 ± 0.5	4.0	4.0	
Minimum Hold Time	t _h		3.3 ± 0.3	1.0	1.0	
			5.0 ± 0.5	1.0	1.0	
Minimum Removal Time (CLR)	t _{rem}		3.3 ± 0.3	6.0	6.0	
			5.0 ± 0.5	3.5	3.5	

AC ELECTRICAL CHARACTERISTICS ($C_L = 50\text{pF}$, $R_L = 500\Omega$, Input $t_r = t_f = 3\text{ns}$)

PARAMETER	SYMBOL	TEST CONDITION	Ta = 25°C			Ta = -40~85°C		UNIT	
			V _{CC} (V)	MIN.	TYP.	MAX.	MIN.		MAX.
Propagation Delay Time (CK-Q)	t_{pLH} t_{pHL}		3.3 ± 0.3	—	8.5	14.4	1.0	16.6	ns
			5.0 ± 0.5	—	6.7	9.6	1.0	11.0	
Propagation Delay Time ($\overline{\text{CLR}}$ -Q)	t_{pHL}		3.3 ± 0.3 5.0 ± 0.5	— —	8.2 6.3	13.9 9.0	1.0 1.0	16.0 10.4	
Maximum Clock Frequency	f_{MAX}		3.3 ± 0.3 5.0 ± 0.5	60 90	110 150	— —	60 90	— —	MHz
Input Capacitance	C_{IN}			—	5	10	—	10	pF
Power Dissipation Capacitance	$C_{\text{PD}}(1)$			—	74	—	—	—	

Note(1) C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

Average operating current can be obtained by the equation :

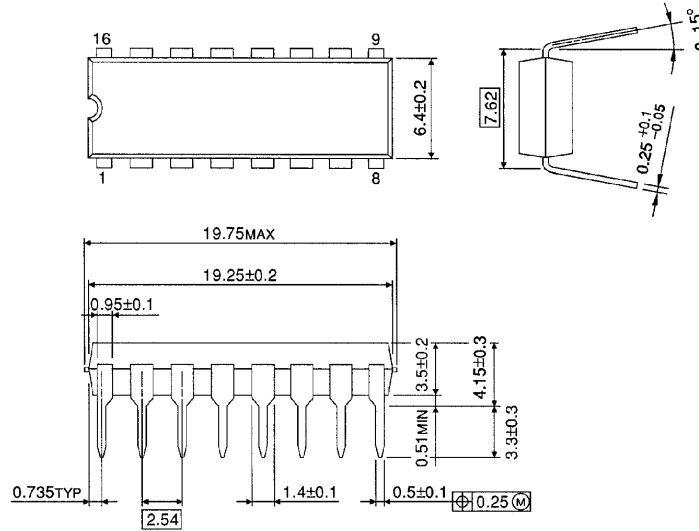
$$I_{\text{CC}}(\text{opr.}) = C_{\text{PD}} \cdot V_{\text{CC}} \cdot f_{\text{IN}} + I_{\text{CC}} / 6 \text{ (per F/F)}$$

And the total CPD when n pcs of Flip Flop operate can be gained by the following equation

$$C_{\text{PD}}(\text{total}) = 34 + 40 \cdot n$$

DIP 16PIN PACKAGE DIMENSIONS (DIP16-P-300-2.54A)

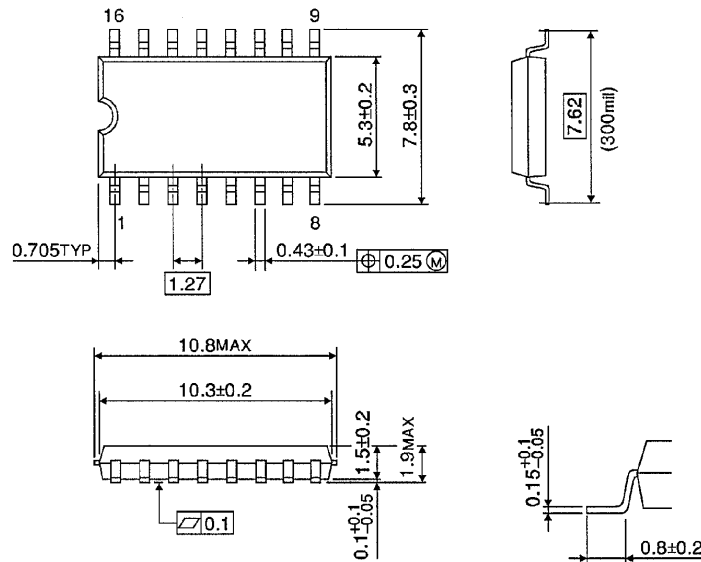
Unit in mm



Weight : 1.00g (Typ.)

SOP 16PIN (200mil BODY) PACKAGE DIMENSIONS (SOP16-P-300-1.27)

Unit in mm

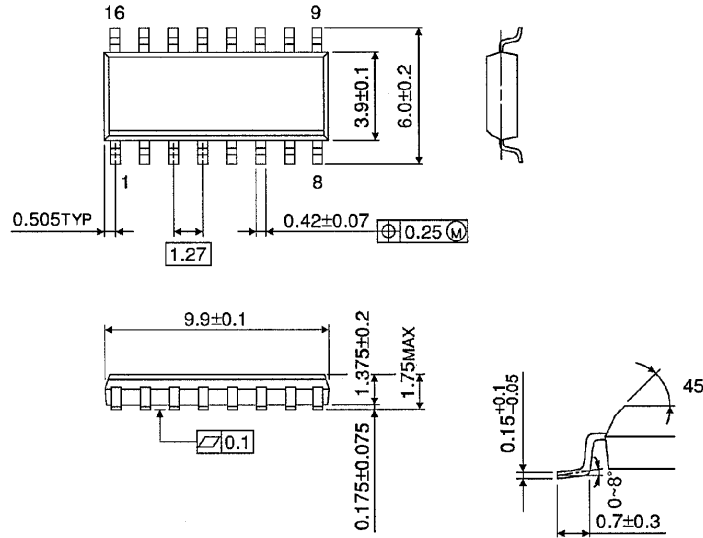


Weight : 0.18g (Typ.)

SOP 16PIN (150mil BODY) PACKAGE DIMENSIONS (SOL16-P-150 -1.27)

Unit in mm

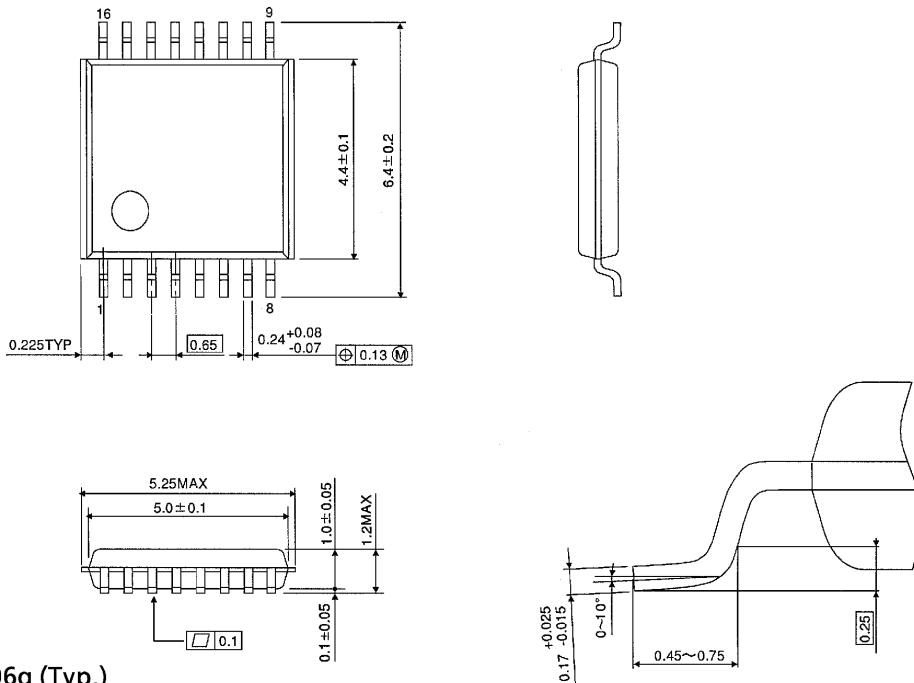
(Note) This package is not available in Japan.



Weight : 0.13g (Typ.)

TSSOP 16PIN PACKAGE DIMENSIONS (TSSOP16-P-0044-0.65)

Unit in mm



Weight : 0.06g (Typ.)

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